

10/6/05 78

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Search Results -

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| L4 and ball | 9 |

Database:

US Pre-Grant Publication Full-Text Database
 US Patents Full-Text Database
 US OCR Full-Text Database
 EPO Abstracts Database
 JPO Abstracts Database
 Derwent World Patents Index
 IBM Technical Disclosure Bulletins

Search:

L5

Refine Search

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Search History

DATE: Tuesday, June 22, 2004 [Printable Copy](#) [Create Case](#)

Set Name Query

side by side

DB=USPT; PLUR=YES; OP=ADJ

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result set

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| <u>L5</u> | L4 and ball | 9 | <u>L5</u> |
| <u>L4</u> | L3 and (wire near5 pad) | 11 | <u>L4</u> |
| <u>L3</u> | L2 and (passivation near (layer or material or film)) | 16 | <u>L3</u> |
| <u>L2</u> | L1 and (wire near5 cavity) | 297 | <u>L2</u> |
| <u>L1</u> | wire adj bond | 7145 | <u>L1</u> |

END OF SEARCH HISTORY

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Search Results - Record(s) 1 through 9 of 9 returned.

☐ 1. Document ID: US 6727579 B1

L5: Entry 1 of 9

File: USPT

Apr 27, 2004

US-PAT-NO: 6727579

DOCUMENT-IDENTIFIER: US 6727579 B1

TITLE: ELECTRICAL CONTACT STRUCTURES FORMED BY CONFIGURING A FLEXIBLE WIRE TO HAVE A SPRINGABLE SHAPE AND OVERCOATING THE WIRE WITH AT LEAST ONE LAYER OF A RESILIENT CONDUCTIVE MATERIAL, METHODS OF MOUNTING THE CONTACT STRUCTURES TO ELECTRONIC COMPONENTS, AND APPLICATIONS FOR EMPLOYING THE CONTACT STRUCTURES

| Full | Title | Citation | Front | Review | Classification | Date | Reference | Claims | KMCL | Draw De |
|------|-------|----------|-------|--------|----------------|------|-----------|--------|------|---------|
|------|-------|----------|-------|--------|----------------|------|-----------|--------|------|---------|

☐ 2. Document ID: US 6478212 B1

L5: Entry 2 of 9

File: USPT

Nov 12, 2002

US-PAT-NO: 6478212

DOCUMENT-IDENTIFIER: US 6478212 B1

TITLE: Bond pad structure and method for reduced downward force wirebonding

| Full | Title | Citation | Front | Review | Classification | Date | Reference | Claims | KMCL | Draw De |
|------|-------|----------|-------|--------|----------------|------|-----------|--------|------|---------|
|------|-------|----------|-------|--------|----------------|------|-----------|--------|------|---------|

☐ 3. Document ID: US 6452406 B1

L5: Entry 3 of 9

File: USPT

Sep 17, 2002

US-PAT-NO: 6452406

DOCUMENT-IDENTIFIER: US 6452406 B1

**** See image for Certificate of Correction ****

TITLE: Probe structure having a plurality of discrete insulated probe tips

| Full | Title | Citation | Front | Review | Classification | Date | Reference | Claims | KMCL | Draw De |
|------|-------|----------|-------|--------|----------------|------|-----------|--------|------|---------|
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☐ 4. Document ID: US 6336269 B1

L5: Entry 4 of 9

File: USPT

Jan 8, 2002

US-PAT-NO: 6336269

DOCUMENT-IDENTIFIER: US 6336269 B1

TITLE: Method of fabricating an interconnection element

| Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KWIC | Draw D |
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|------|--------|
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☐ 5. Document ID: US 6110823 A

L5: Entry 5 of 9

File: USPT

Aug 29, 2000

US-PAT-NO: 6110823

DOCUMENT-IDENTIFIER: US 6110823 A

TITLE: Method of modifying the thickness of a plating on a member by creating a temperature gradient on the member, applications for employing such a method, and structures resulting from such a method

| Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KWIC | Draw D |
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|------|--------|
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☐ 6. Document ID: US 5635424 A

L5: Entry 6 of 9

File: USPT

Jun 3, 1997

US-PAT-NO: 5635424

DOCUMENT-IDENTIFIER: US 5635424 A

TITLE: High-density bond pad layout arrangements for semiconductor dies, and connecting to the bond pads

| Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KWIC | Draw D |
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|------|--------|
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☐ 7. Document ID: US 5565385 A

L5: Entry 7 of 9

File: USPT

Oct 15, 1996

US-PAT-NO: 5565385

DOCUMENT-IDENTIFIER: US 5565385 A

TITLE: Semiconductor bond pad structure and increased bond pad count per die

| Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KWIC | Draw D |
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|------|--------|
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☐ 8. Document ID: US 5441917 A

L5: Entry 8 of 9

File: USPT

Aug 15, 1995

US-PAT-NO: 5441917

DOCUMENT-IDENTIFIER: US 5441917 A

TITLE: Method of laying out bond pads on a semiconductor die

| Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KMC | Draw De |
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|-----|---------|
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☐ 9. Document ID: US 5404047 A

L5: Entry 9 of 9

File: USPT

Apr 4, 1995

US-PAT-NO: 5404047

DOCUMENT-IDENTIFIER: US 5404047 A

TITLE: Semiconductor die having a high density array of composite bond pads

| Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KMC | Draw De |
|------|-------|----------|-------|--------|----------------|------|-----------|--|--|--------|-----|---------|
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